g GE Energy	**Functional Testing Specification**
Parts & Repair Services ***Louisville, KY***	**LOU-GED-IS200JPDV**

Test Procedure for an IS2020JPDV Power Distribution Card.

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

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1. SCOPE

1.1 This is a functional testing procedure for an **IS200JPDV** Power Distribution Card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.
3.1.1 Check board's electronic folder for more information.

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning
4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.
4.2 Equipment Inspection
4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:
4.2.1.1 Wires - broken, cracked, or loosely connected
4.2.1.2 Terminal strips / connectors - broken or cracked
4.2.1.3 Components - visually damaged
4.2.1.4 Capacitors - bloated or leaking
4.2.1.5 Solder joints - damaged or cold
4.2.1.6 Circuit board - burned or de-laminated
4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)

6. TESTING PROCESS

6.1 Static Checks

6.1.1 Using a multimeter set for Resistance function, check points for the expected results in the following table: You may have to "REL" out the leads to get expected results.

From:	To:	Expected Result:
PB1	JA1-28	<1 Ohm
PB1	JA1-31	<1 Ohm
PB1	Capacitor C1 (side away from JA1)	<1 Ohm
PB1	Capacitor C2 (side away from JB1)	<1 Ohm
PB1	MV1 (side closest to JB1)	<1 Ohm
PB1	Connector JX1-3	<1 Ohm
E1 (Eyelet)	E2 (Eyelet)	<1 Ohm
E1 (Eyelet)	E3 (Eyelet)	<1 Ohm
E1 (Eyelet)	E4 (Eyelet)	<1 Ohm
E1 (Eyelet)	JP4-2	<1 Ohm
E1 (Eyelet)	JP5-2	<1 Ohm
E1 (Eyelet)	JP6-2	<1 Ohm
E1 (Eyelet)	JP7-2	<1 Ohm
E1 (Eyelet)	JP8-2	<1 Ohm
E1 (Eyelet)	JP9-2	<1 Ohm
E1 (Eyelet)	JP10-2	<1 Ohm
E1 (Eyelet)	JP28-3	<1 Ohm
E1 (Eyelet)	JP28-4	<1 Ohm
JP10-1	JP4-1	<1 Ohm
JP10-1	JP4-3	<1 Ohm
JP10-1	JP5-1	<1 Ohm
JP10-1	JP5-3	<1 Ohm
JP10-1	JP6-1	<1 Ohm
JP10-1	JP7-1	<1 Ohm
JP10-1	JP8-1	<1 Ohm
JP10-1	JP9-1	<1 Ohm
JP10-1	JP28-1	<1 Ohm
JP10-1	JP28-2	<1 Ohm
JA1-29	JARC-S (center)	<1 Ohm
JA1-30	JARC-G (outside)	<1 Ohm
JA1-30	MV1 (side furthest away from JB1)	<1 Ohm

JB1-32	JX1A-1	<1 Ohm
From:	**To:**	**Expected Result:**
JB1-33	JX1A-2	<1 Ohm
Capacitor C1 (side closest to JA1)	JA1 Shield	<1 Ohm
Capacitor C2 (side closest to JB1)	JB1 Shield	<1 Ohm

6.1.2 CHIP ID: The ID chip needs to be read to confirm that it has been programmed properly. Take the card over to the CHIP ID pc located in the MARK VI area of the shop and select the correct revision of IS200JPDC from the menu and follow the instructions given to you by the pc. When selecting which IS200JPDC to use, you may see a 5G or 7G next to the number. This refers to the serial number and whether it has 5 or 7 digits in it. Select the proper one, as you will be expected to type this number into the system at a given point. When entering this data, be sure to use all CAPITAL LETTERS as lower case might cause it not to agree with what's programmed in the chip. If the particular revision you need to select doesn't have a 5G or 7G next to it, get it added before proceeding.

6.2 ***TEST COMPLETE ***

7. NOTES

7.1 None at this time.

8. ATTACHMENTS

8.1 None at this time.